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(54) Fuzzy logic control of thermoelectric cooling in a processor

(57) In an embodiment, a processor includes a fuzzy thermoelectric cooling (TEC) controller to: obtain a current TEC level associated with the processor; obtain a current fan power level associated with the processor; fuzzify the current TEC level to obtain a first fuzzy fan level; fuzzify the current fan power level to obtain a second fuzzy fan level; determine a new TEC power level based at least in part on the first fuzzy fan level, the second fuzzy fan level, and a plurality of fuzzy rules; and provide the new TEC power level to a TEC device associated with the processor, where the TEC device is to transfer heat from the processor to a heat sink. Other embodiments are described and claimed.

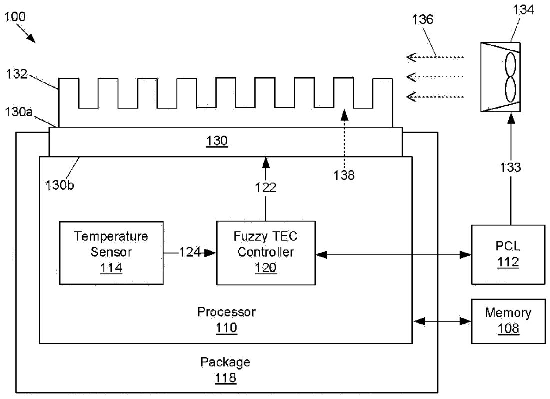

FIG. 1A

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